



RECOMMENDED P.C. BOARD LAYOUT

CKT. SIZE	DIMENSION A		DIMENSION B	
	(MM)	INCH	(MM)	INCH
4	(2.54)	.100	(4.83)	.190
6	(5.08)	.200	(7.37)	.290
8	(7.62)	.300	(9.91)	.390
10	(10.16)	.400	(12.45)	.490
12	(12.70)	.500	(14.99)	.590
14	(15.24)	.600	(17.53)	.690
16	(17.78)	.700	(20.07)	.790
18	(20.32)	.800	(22.61)	.890
20	(22.86)	.900	(25.15)	.990
22	(25.40)	1.000	(27.69)	1.090
24	(27.94)	1.100	(30.23)	1.190
26	(30.48)	1.200	(32.77)	1.290
28	(33.02)	1.300	(35.31)	1.390
30	(35.56)	1.400	(37.85)	1.490
32	(38.10)	1.500	(40.39)	1.590
34	(40.64)	1.600	(42.93)	1.690
36	(43.18)	1.700	(45.47)	1.790
38	(45.72)	1.800	(48.01)	1.890
40	(48.26)	1.900	(50.55)	1.990
42	(50.80)	2.000	(53.09)	2.090
44	(53.34)	2.100	(55.63)	2.190
46	(55.88)	2.200	(58.17)	2.290
48	(58.42)	2.300	(60.71)	2.390
50	(60.96)	2.400	(63.25)	2.490
52	(63.50)	2.500	(65.79)	2.590
54	(66.04)	2.600	(68.33)	2.690
56	(68.58)	2.700	(70.87)	2.790
58	(71.12)	2.800	(73.41)	2.890
60	(73.66)	2.900	(75.95)	2.990
62	(76.20)	3.000	(78.49)	3.090
64	(78.74)	3.100	(81.03)	3.190
66	(81.28)	3.200	(83.57)	3.290
68	(83.82)	3.300	(86.11)	3.390
70	(86.36)	3.400	(88.65)	3.490
72	(88.90)	3.500	(91.19)	3.590
74	(91.44)	3.600	(93.73)	3.690
76	(93.98)	3.700	(96.27)	3.790
78	(96.52)	3.800	(98.81)	3.890
80	(99.06)	3.900	(101.35)	3.990

NOTES:

- PIN PUSHOUT FORCE: 4 LBS. MINIMUM (IN EITHER DIRECTION)
- FOR ILLUSTRATION PURPOSES, 20 (DUAL 10) CIRCUIT SIZE IS SHOWN.
- PINS MUST MEET MOLEX SOLDERABILITY SPECIFICATION ES-152, EXCEPT VOIDS ARE PERMISSIBLE AT BANDOLIER PIN FAYING SURFACE (APPROX. .025 LONG X .006 WIDE REF.- 2 LOCATIONS).
- MEASURE POINT FOR PLATING THICKNESS.
- THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-8624.
- PACKAGING INFORMATION: (UNLESS OTHERWISE NOTED IN TABLES) PER PACKAGING DRAWING NO. PK-70873-0353 BULK PACKAGED IN BAGS

PLATING:

- TIN - .000150 MINIMUM TIN PLATE OVER .000050 MINIMUM NICKEL PLATE.
- 15 GOLD - .000015 MINIMUM GOLD PLATE IN SELECT AREA, .000075 MINIMUM TIN PLATE IN SELECT AREA, OVER .000050 MINIMUM NICKEL PLATE OVERALL.
- 30 GOLD - .000030 MINIMUM GOLD PLATE IN SELECT AREA, .000075 MINIMUM TIN PLATE IN SELECT AREA, OVER .000050 MINIMUM NICKEL PLATE OVERALL.
- D30 GOLD - .000030 MINIMUM GOLD PLATE IN SELECT AREAS OVER .000050 MINIMUM NICKEL PLATE OVERALL.
- 5 GOLD - .000005 MINIMUM GOLD FLASH IN SELECT AREA, .000075 MINIMUM TIN PLATE IN SELECT AREA, OVER .000050 MINIMUM NICKEL PLATE OVERALL.

MATERIAL:

- WAFER - GLASS FILLED POLYESTER; UL94V-0; COLOR: BLACK
- PIN - PHOSPHOR BRONZE

*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.

DIMENSIONS SHOWN (METRIC) INCH UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°		▽ = 0		= 0		REVISE ONLY ON CAD SYSTEM	
3 PLACE ± .005		INCH		METRIC		TITLE	
2 PLACE ± .01 ± 0.13		1 PLACE ± 0.25		SALES ASSY-DUAL ROW WAFER W/BREAK-OFF OPTION .025 SQ. PINS/.100 GRID		MFG, SH, REV, LTR, REVISIONS	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MOLEX INCORPORATED		SHEET NO. DATE		1 OF 7 11/30/88	
DRWG. BY: EIK		CHK'D. BY: AAB		PART NO.		DRWG. NO.	
APP'D. BY: WAZ		SCALE: 4:1		FILE NAME: S8624X1		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

